



Material Content Data Sheet



Sales Product Name				IPL60R199CP		Issued		27. September 2017	
MA#				MA000842392					
Package				PG-VSON-4-1		Weight*		190.71 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	8.809	4.62	4.62	46191	46191	
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		67		
	non noble metal	zinc	7440-66-6	0.051	0.03		267		
	non noble metal	iron	7439-89-6	1.017	0.53		5334		
wire	non noble metal	copper	7440-50-8	41.300	21.66	22.23	216565	222233	
	non noble metal	copper	7440-50-8	0.991	0.52	0.52	5194	5194	
	encapsulation	organic material	carbon black	1333-86-4	0.210	0.11		1099	
	plastics	epoxy resin	-	10.791	5.66		56585		
	inorganic material	silicondioxide	60676-86-0	93.768	49.16	54.93	491684	549368	
leadfinish	non noble metal	tin	7440-31-5	2.397	1.26	1.26	12572	12572	
plating	noble metal	silver	7440-22-4	0.252	0.13	0.13	1321	1321	
solder	noble metal	silver	7440-22-4	0.151	0.08		793		
	non noble metal	tin	7440-31-5	0.121	0.06		635		
	non noble metal	lead	7439-92-1	5.779	3.03	3.17	30305	31733	
heatspreader	inorganic material	phosphorus	7723-14-0	0.008	0.00		39		
	non noble metal	zinc	7440-66-6	0.030	0.02		158		
	non noble metal	iron	7439-89-6	0.601	0.32		3153		
	non noble metal	copper	7440-50-8	24.418	12.80	13.14	128038	131388	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com